PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT5651530

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Kun-Ju Li	07/30/2019
Tai-Cheng Hou	07/30/2019
Hsin-Jung Liu	07/30/2019
Fu-Yu Tsai	07/30/2019
Bin-Siang Tsai	07/30/2019
Chau-Chung Hou	07/30/2019
Yu-Lung Shih	07/30/2019
Ang Chan	07/30/2019
Chih-Yueh Li	07/30/2019
Chun-Tsen Lu	07/30/2019

RECEIVING PARTY DATA

Name:	UNITED MICROELECTRONICS CORP.
Street Address:	No.3, Li-Hsin Road 2, Science-Based Industrial Park
City:	Hsin-Chu City
State/Country:	TAIWAN

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	16531108

CORRESPONDENCE DATA

Fax Number: (703)997-4517

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 3027291562
Email: Patent.admin.uspto.cr@naipo.com
Correspondent Name: WINSTON HSU
Address Line 1: 5F., NO.389, FUHE RD., YONGHE DIST.,
Address Line 4: NEW TAIPEI CITY, TAIWAN

ATTORNEY DOCKET NUMBER:	NAUP3468USA
NAME OF SUBMITTER:	SIBYL YU

SIGNATURE:	/SIBYL YU/
DATE SIGNED:	08/04/2019

Total Attachments: 20

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Docket No NAUP3468USA

COMBINE DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT

Title of Invention:
SEMICONDUCTOR DEVICE AND METHOD FOR FABRICATING THE SAME

As the below named inventor, I hereby declare that:
This declaration is directed to:

☑ The attached application, or

☐ United States application number ________________ filed on ____________, or

☐ PCT international application number ________________ filed on ____________

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I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.

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In consideration of the payment by **UNITED MICROELECTRONICS CORP.** having a postal address of

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(referred to as "ASSIGNEE"below) to I of the sum of One Dollar ($ 1.00), the receipt of which is hereby acknowledged, andfor other good and valuable consideration.

I hereby sell, assign and transfer to ASSIGNEE and the successors and assignees of the ASSIGNEE the entire right, title and interest in and to any and all improvements which are disclosed in the invention as above-identified application and, in and to, all Letters Patent to be obtained for said invention by the above application or any continuations, continuation-in-part, divisions, renewals, substitutes, or extensions thereof, and as to Letters Patent any reissue or re-examination thereof.

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Note: An application data sheet (PTO/SB/14 or equivalent), including naming the entire inventive entity, must accompany this form. Use this form for each additional inventor.

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: **Kun-Ju Li** Date: JUL 30 2019

Signature: Kun-Ju Li

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LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: **Tai-Cheng Hou** Date: JUL 3 0 2019

Signature: Tai-Cheng Hou

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LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: **Hsin-Jung Liu** Date: JUL 3 0 2019

Signature: Hsin-Jung Liu

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LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: **Fu-Yu Tsai** Date: JUL 30 2019

Signature: Fu-Yu Tsai

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LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: **Bin-Siang Tsai** Date: JUL 30 2019

Signature: Bin-Siang Tsai

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LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: **Chau-Chung Hou** Date: JUL 3 0 2019

Signature: Chau-Chung Hou

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LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: **Yu-Lung Shih** Date: JUL 3 0 2019

Signature: Yu-Lung Shih

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Inventor: **Ang Chan** Date: JUL 3 0 2019

Signature: Ang Chan

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Inventor: **Chun-Tsen Lu** Date: JUL 3 0 2019

Signature: Chun-Tsen Lu